



Optical Link of the ATLAS Pixel Detector

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Outline



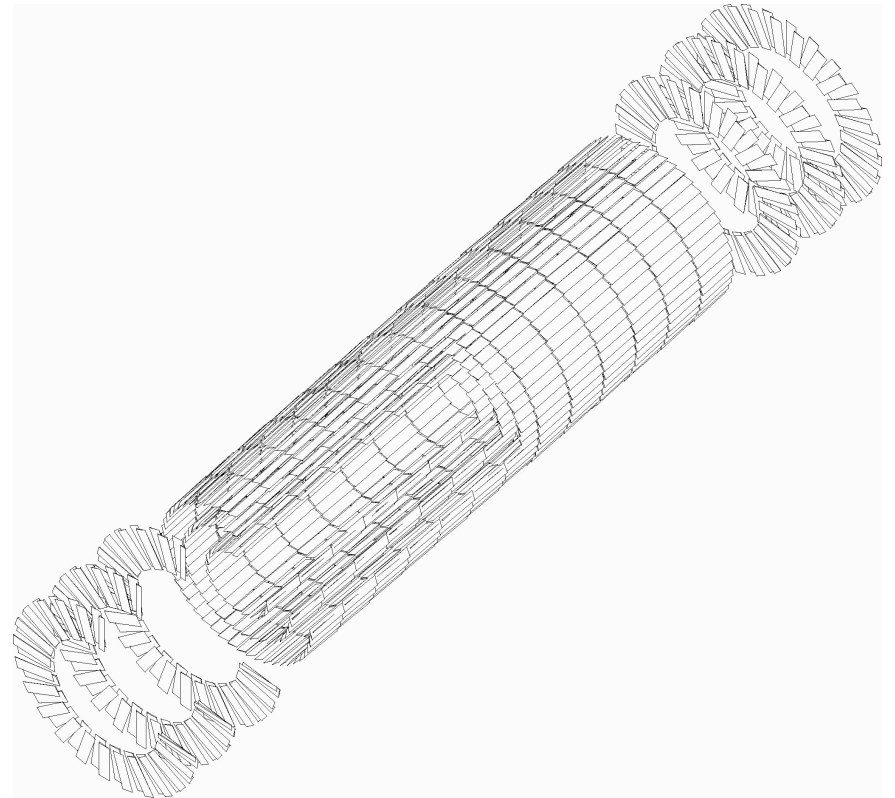
- Introduction
- Proton Irradiation Studies
- Production Status
- Summary



ATLAS Pixel Detector

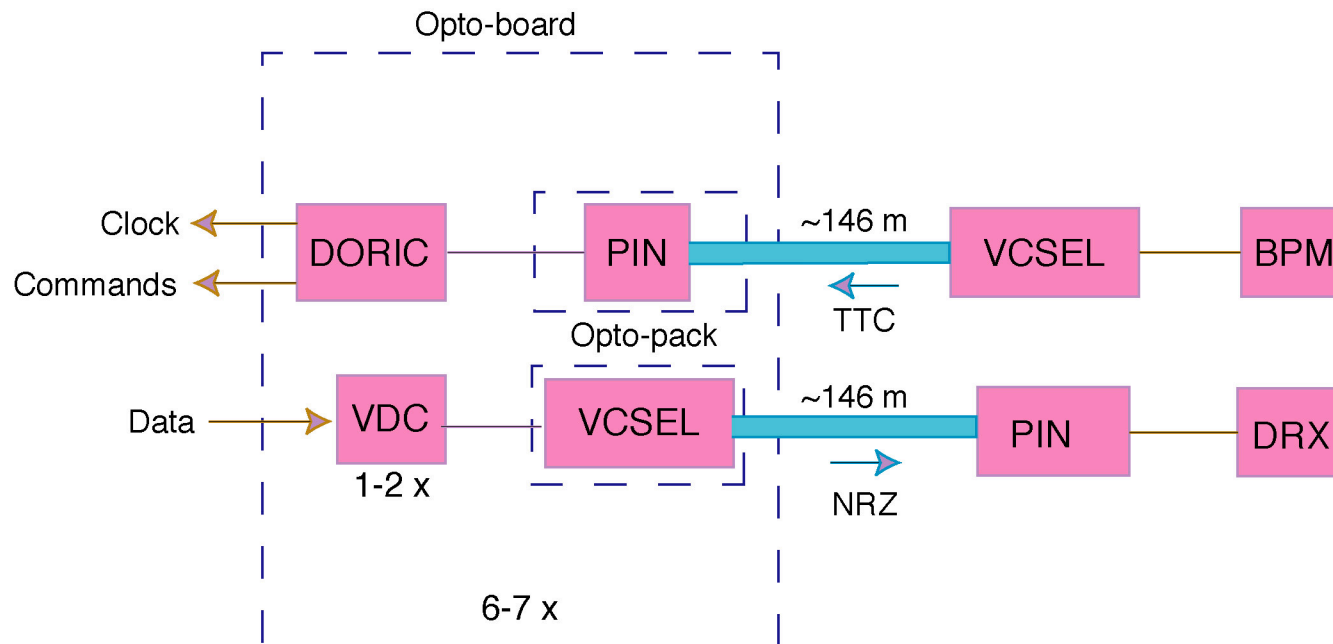


- Inner most tracking detector
- Pixel size: $50\ \mu\text{m} \times 400\ \mu\text{m}$
- 100 million channels
- Barrel layers at $r = 5.1\text{-}12.3\ \text{cm}$
- Disks at $z = 50\text{-}65\ \text{cm}$
- Dosage after 10 years:
 - ◆ optical link: $17\ \text{Mrad}$ or $3.7 \times 10^{14}\ \text{1-MeV}\ n_{\text{eq}}/\text{cm}^2$





ATLAS Pixel Opto-link



VCSEL: Vertical Cavity Surface Emitting Laser diode

VDC: VCSEL Driver Circuit

PIN: PiN diode

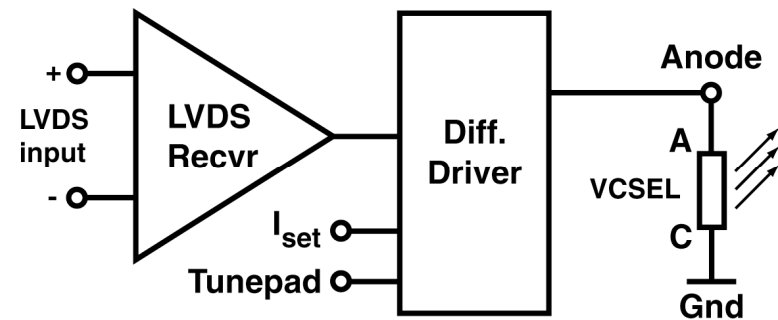
DORIC: Digital Optical Receiver Integrated Circuit



VDC: VCSEL Driver Circuit



- Convert **LVDS** input signal into **single-ended** signal appropriate to drive **VCSEL** diode
- Output (bright) current: **0 to 20 mA**
 - ◆ controlled by external current I_{set}
- Standing (dim) current: **~ 1 mA**
 - ◆ improve switching speed
- Rise & fall times: **1 ns** nominal for **40 MHz** signals
- “On” voltage of VCSEL: up to **2.3 V** at 20 mA for 2.5 V supply
- **Constant** current consumption!
- Use IBM 0.25 μm CMOS
- Use Truelight high-power oxide common cathode VCSEL array

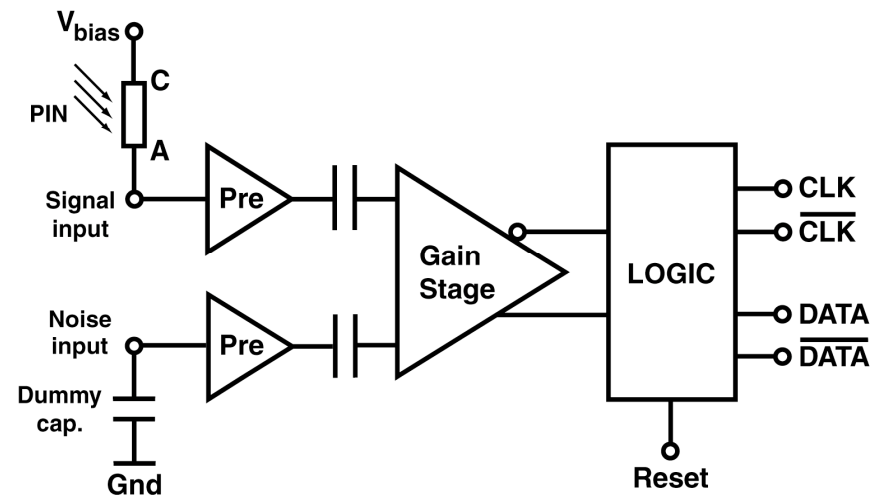
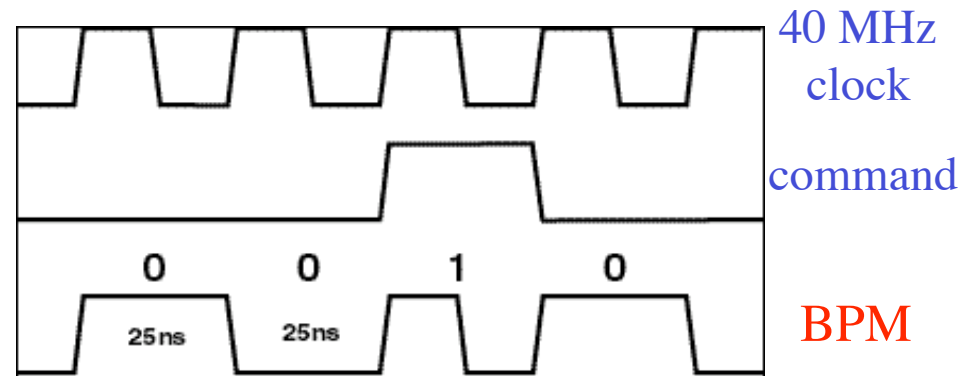




DORIC: Digital Optical Receiver IC



- Decode Bi-Phase Mark encoded (BPM) clock and command signals from PIN diode
- Input signal: 40-1000 μA
- Extract: 40 MHz clock
- Duty cycle: $(50 \pm 4)\%$
- Total timing error: $< 1 \text{ ns}$
- Bit Error Rate (BER): $< 10^{-11}$ at end of life
- Use IBM 0.25 μm CMOS
- Use Truelight common cathode PIN array (Taiwan)



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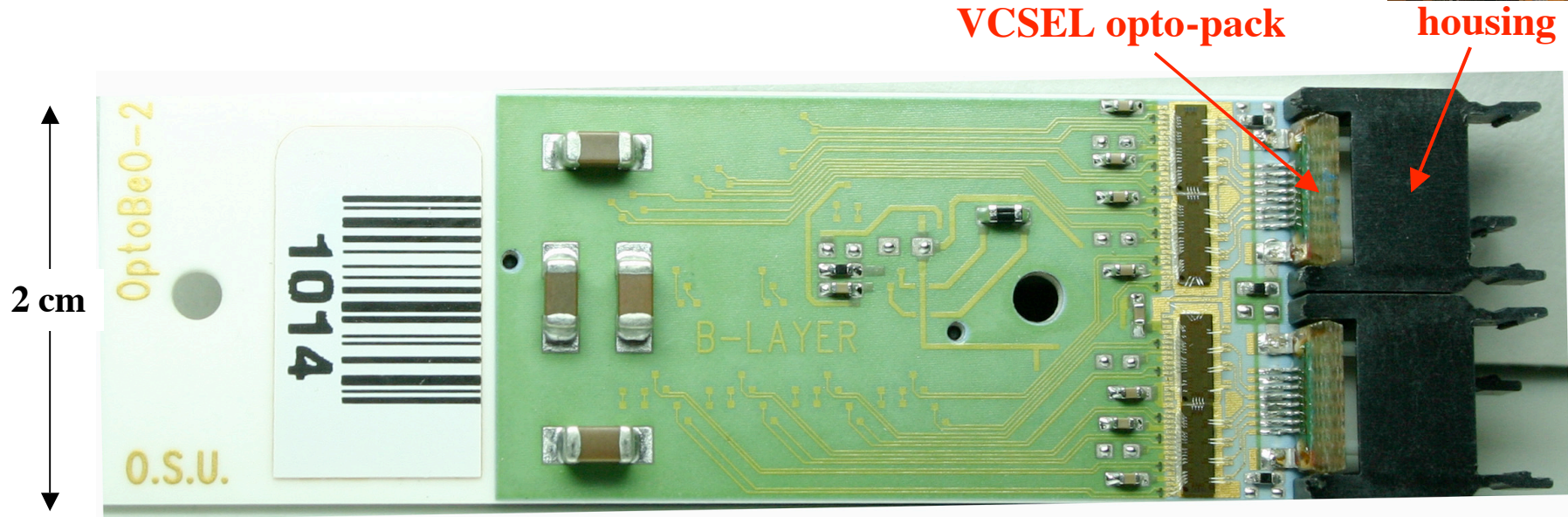
Status of BeO Opto-board



- converts: optical signal ↔ electrical signal
- contains 7 optical links
- use BeO for heat management but prototype initially in FR-4 for fast turnaround and cost saving
- 1st BeO vendor:
 - ◆ either under or over filling of vias
 - ⇒ use more experienced/expensive vendor
- 2nd BeO vendor:
 - ◆ 1st prototype: 1-2 SMD detached from few boards
 - ⇒ remove gold under SMD pads
 - ◆ 2nd prototype: SMD pads have much better adhesion
 - ⇒ remove gold under 80-pin connector pads
 - ⇒ order production opto-boards



BeO Opto-board



VCSEL opto-pack

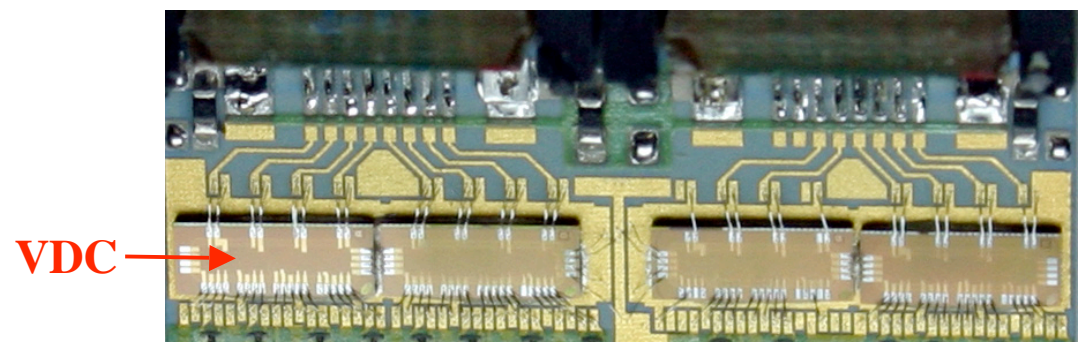
housing

2 cm

OptoBeO-2
1014
O.S.U.

B-LAYER

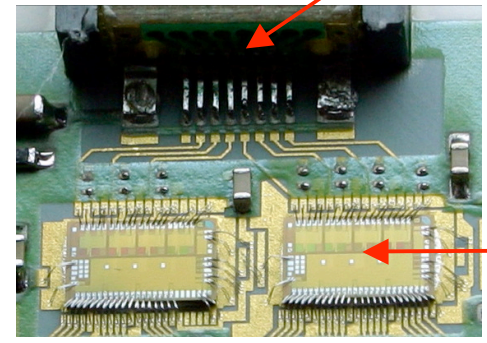
PIN opto-pack



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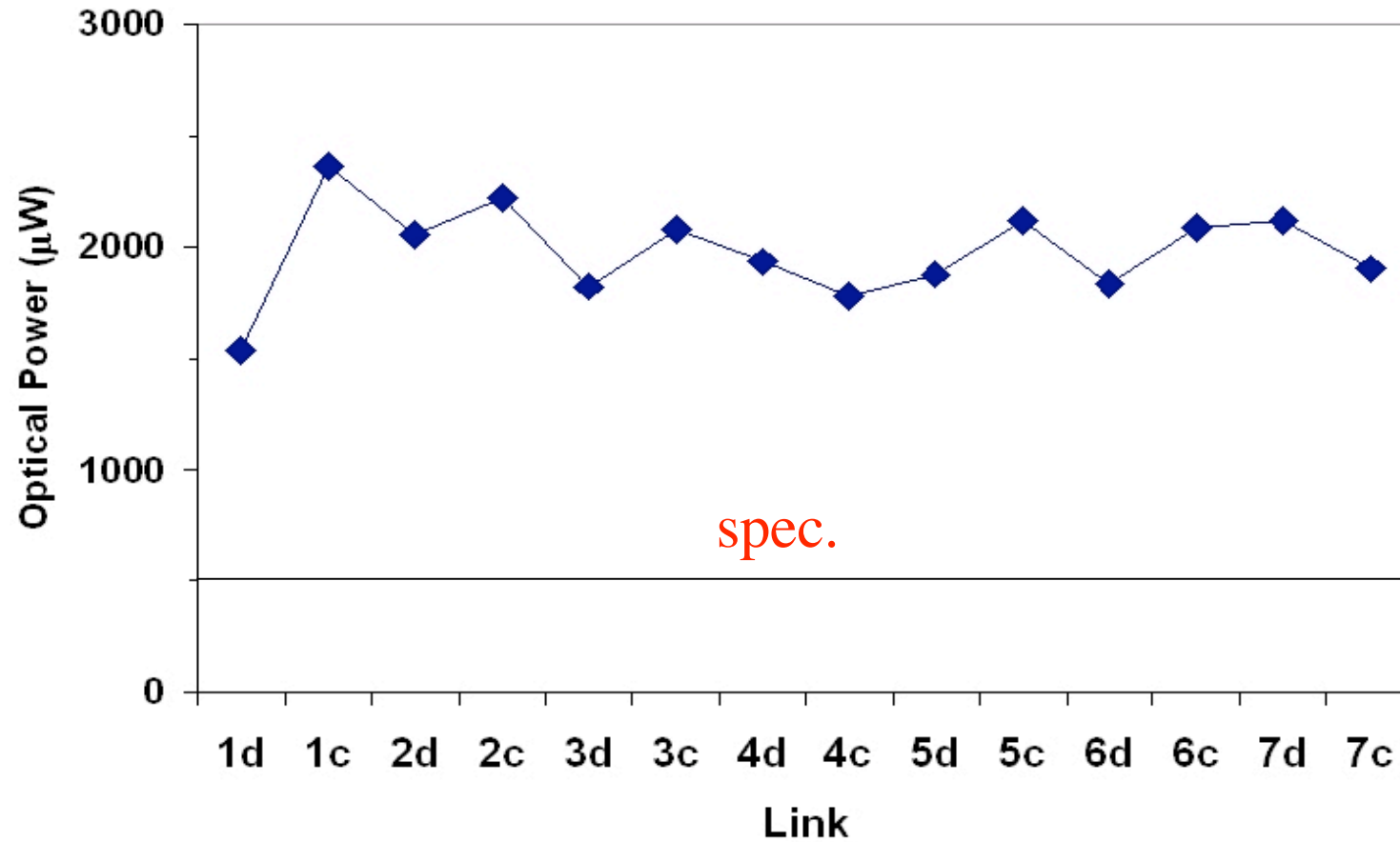


DORIC

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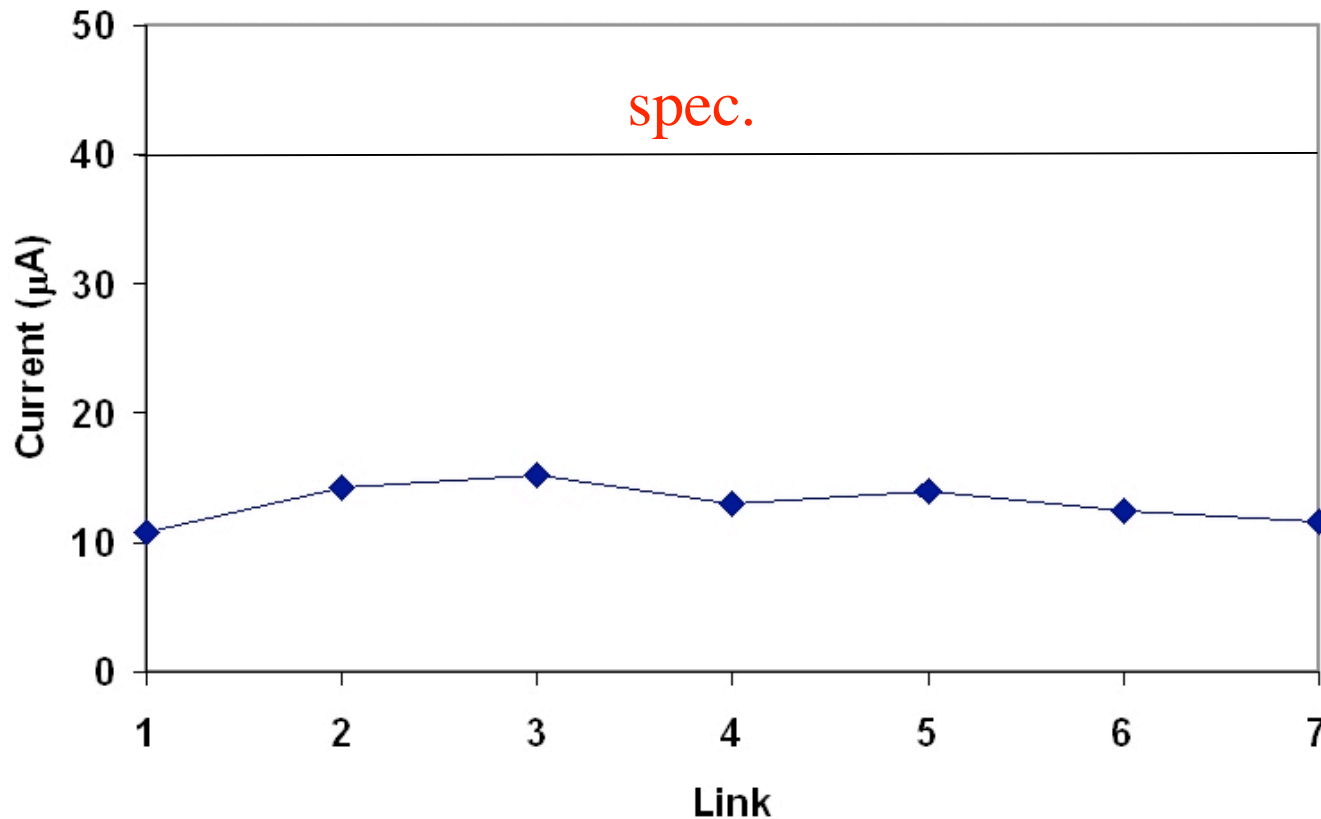
Optical Power



- optical power at 10 mA significantly above spec, 500 μW



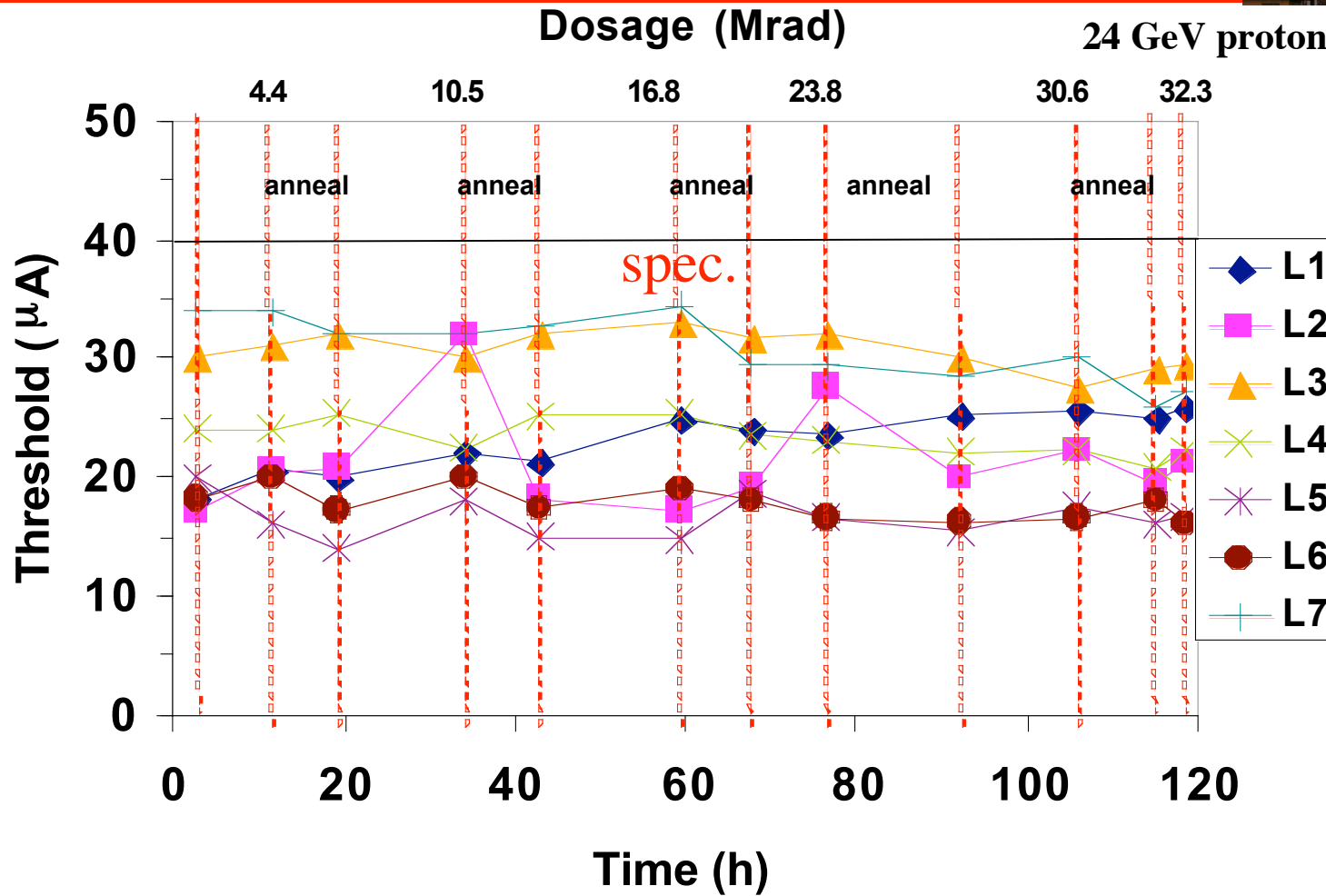
Minimum PIN Current for No Bit Errors



- minimum PIN current for no bit errors with all links active significantly below spec, 40 μA



PIN Current Threshold vs Dosage



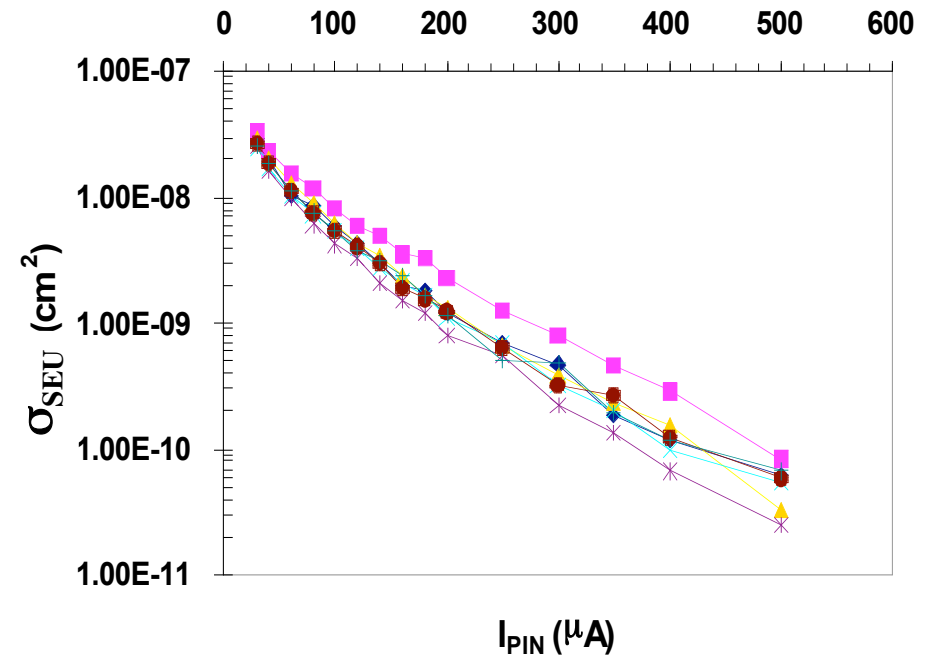
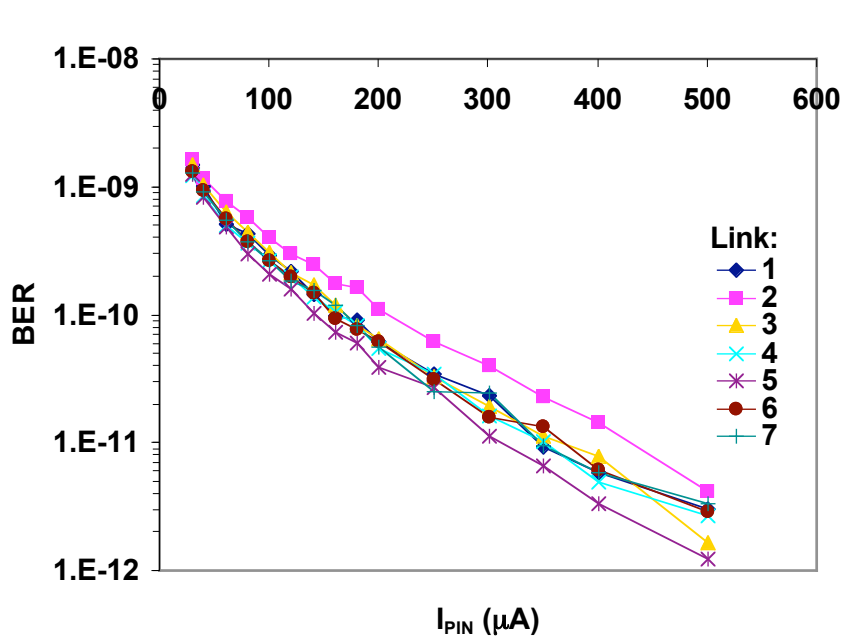
● PIN current thresholds for no bit errors remain constant



Proton Induced Bit Errors in PIN



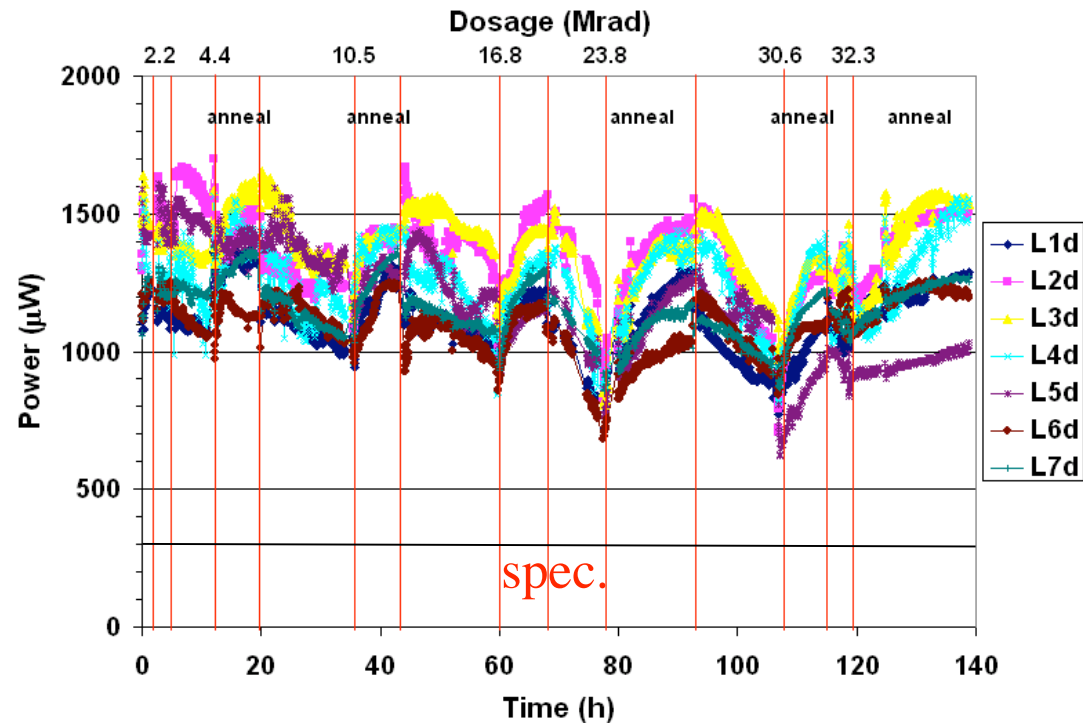
- convert observed bit errors into bit error rate at opto-link location:



- bit error rate decreases with PIN current as expected
- bit error rate $\sim 3 \times 10^{-10}$ at $100 \mu A$ (1.4 errors/minute)
- DORIC spec: 10^{-11}



Optical Power vs Dosage



- irradiation procedure: ~ 5 Mrad/day (10 hours) with annealing rest of the day
- optical power decreases with dosage as expected
- limited annealing recovers some lost power
- still have good optical power after 30 Mrad



Opto-Production Challenges



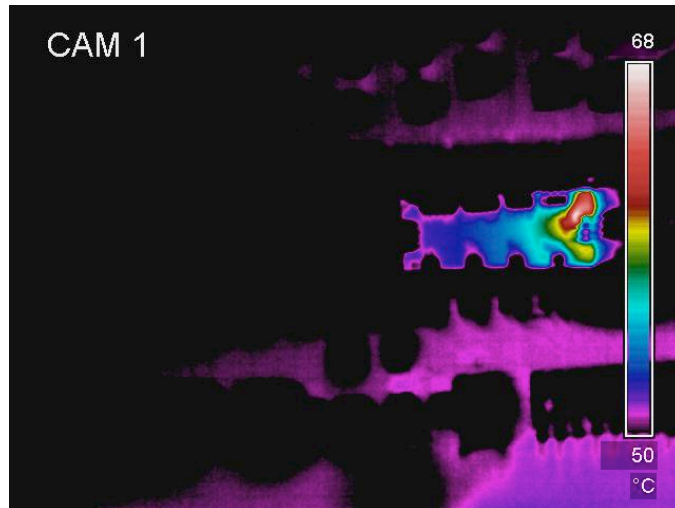
- rigorous QA procedure:
 - ◆ 72 hours of burn-in at 50°C
 - ◆ 18 hours of 10 thermal cycles between -25°C and 50°C
 - ◆ 8 hours of optical and electrical measurements
- use 2 ovens and 2 environmental chambers
- implemented an “early shift” to extend the work day
- aggressive goals:
 - ◆ producing 10 boards/week
 - ◆ complete production by early October



Initial Production Problem

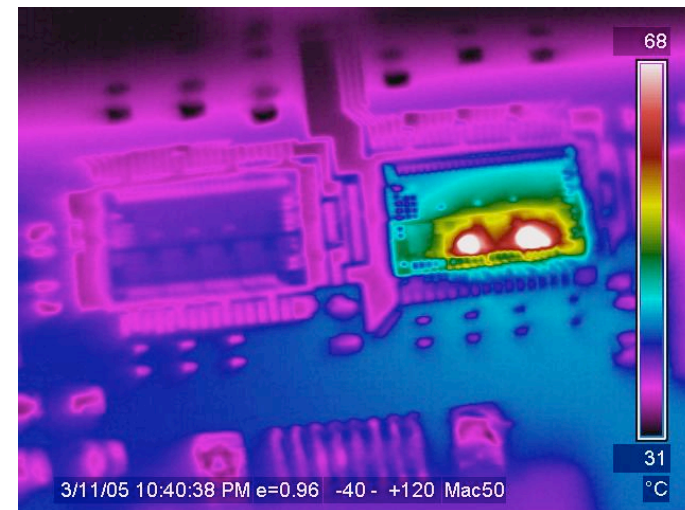


- initial plan was not to test chips before mounting on opto-board due to high yield during pre-production
- a bunch of produced boards drawing excessive currents
 - ◆ thermal image: power to ground shorts
- ⇒ test chips before mounting



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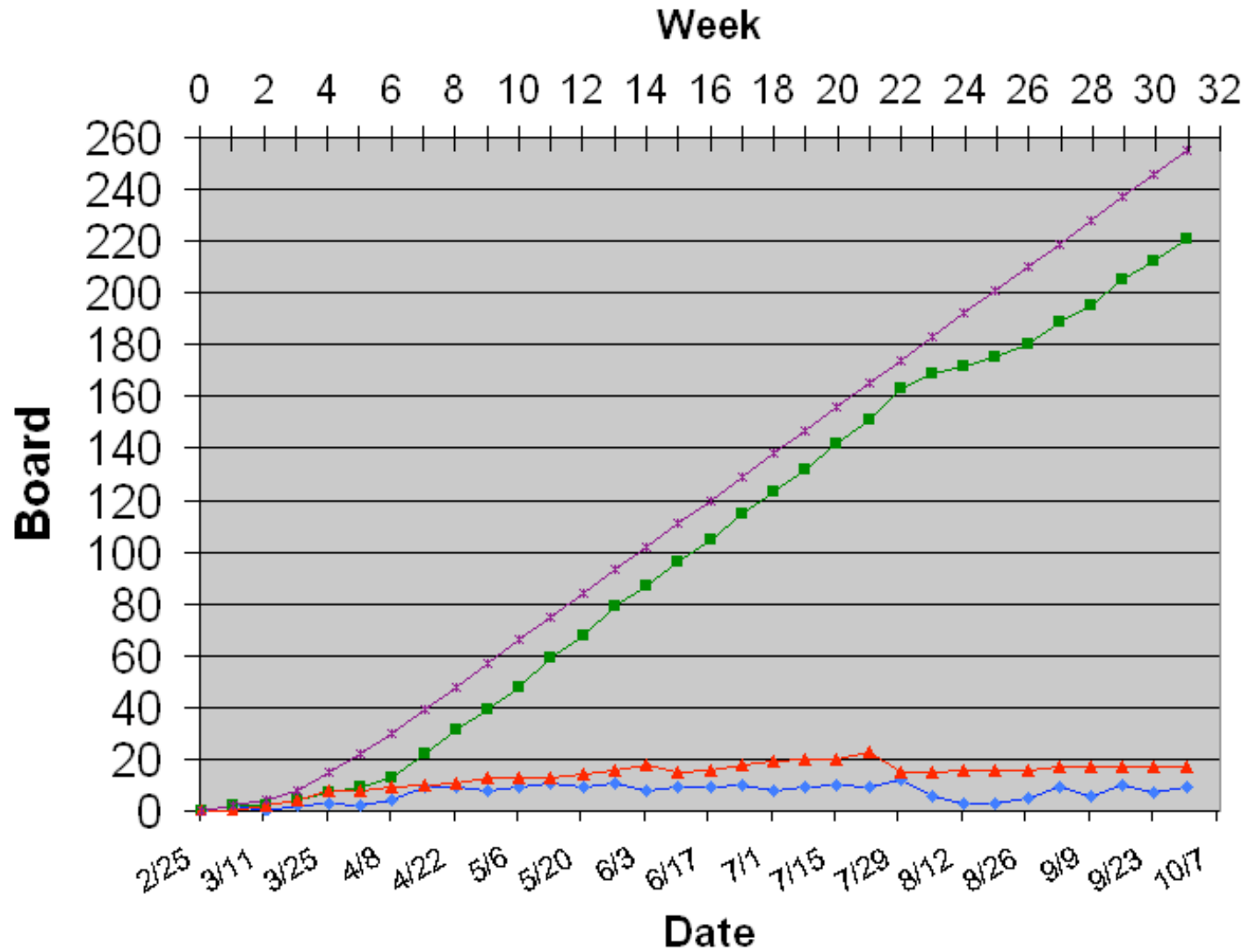
Opto-board Rework



- recover opto-boards by stacking new chips on top of bad chips
- reworked opto-boards must pass same rigorous QA procedure
 - ◆ classified as second class for use as spare
- 18 opto-boards have been recovered



Opto-board Production Status





Summary



- opto-boards of ATLAS pixel detector satisfy design spec. and radiation hardness requirement:
 - ✓ low PIN current thresholds for no bit errors
 - ✓ excellent optical power
 - ✓ radiation hard up to ~ 30 Mrad
- simple and modular design allows smooth production
 - production expected to complete this week